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JFW

Appl No. 10/085,164  
Preliminary Amdt. dated January 27, 2005



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Kelly, et al.

Serial No.: 10/085,164

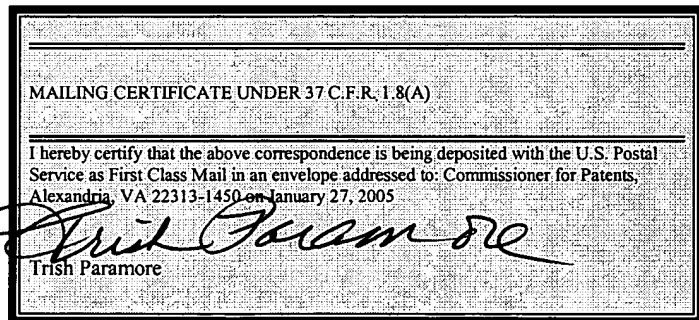
Filed: 02/26/2002

Art Unit: 2814

Examiner: Hoai Pham

For: **ENCAPSULATED DIE PACKAGE WITH IMPROVED PARASITIC  
AND THERMAL PERFORMANCE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450



**PRELIMINARY AMENDMENT**

Sirs and Madams:

Prior to examination, please amend the above-identified application as follows: Please add new Claims 51 to 65 as set forth herein.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 11 of this paper.